

03500.011946



## PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: )  
Akira FUNAKOSHI et al. )  
Application No.: 08/801,464 )  
Filed: February 18, 1997 )  
For: SUBSTRATE CUTTING METHOD AND )  
SUBSTRATE CUTTING APPARATUS :  
)  
: Examiner: C. Dexter  
: Group Art Unit: 3724  
:  
:  
:  
July 23, 2002

COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

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Sir:

Transmitted herewith is an Amendment in the above-identified application.

No additional fee is required.

The fee has been calculated as shown below:

CLAIMS AS AMENDED						
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL CLAIMS	9	MINUS	34	0	x \$ 9 \$18	\$0.00
INDEP. CLAIMS	2	MINUS	6	0	x \$42 \$84	\$0.00
Fee for Multiple Dependent claims \$135°/\$270						
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT---						\$0.00

°Verified Statement claiming small entity status is enclosed, if not filed previously.

- A check in the amount of \$\_\_\_\_\_ is enclosed including the additional claims fees.
- Charge \$\_\_\_\_ to Deposit Account No. 06-1205. A duplicate of this sheet is enclosed.
- Any prior general authorization to charge an issue fee under 37 C.F.R. § 1.18 to Deposit Account No. 06-1205 is hereby revoked. The Commissioner is hereby authorized to charge any additional fees under 37 C.F.R. §§ 1.16 and 1.17 which may be required during the entire pendency of this application, or to credit any overpayment, to Deposit Account No. 06-1205. A duplicate of this paper is enclosed.
- A check in the amount of \$\_\_\_\_\_ to cover the Extension fee for response within \_\_\_\_ additional months is enclosed.
- A check in the amount of \$\_\_\_\_ to cover the Information Disclosure Statement fee is enclosed.
- Applicants' undersigned attorney may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should continue to be directed to our address given below.

Respectfully submitted,

  
Attorney for Applicants  
Steven E. Warner  
Registration No. 33,326

FITZPATRICK, CELLA, HARPER & SCINTO  
30 Rockefeller Plaza  
New York, New York 10112-3801  
Facsimile: (212) 218-2200

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G. Zimmerman  
8/18.

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The Commissioner for Patents  
Washington, D.C. 20231

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AMENDMENT

Sir:

In response to the Official Action dated April 23, 2002, please amend the above-identified application as follows:

IN THE ABSTRACT:

Please substitute the following abstract for the abstract currently presented in the specification. A marked-up copy of the abstract showing the changes made thereto is attached in Appendix A.

41   
-- A method of producing a semiconductor device constructed by arranging a plurality of substrates, on each of which, thin film semiconductor elements two-dimensionally arranged